

## 901-910 SERIES CHIPSET HEAT SINKS



PIN FIN &  
ELLIPTICAL  
HEAT SINKS



Wakefield-Vette's 901-910 Series Heat Sinks for Chipset can match up to devices from Intel, Broadcom, Xilinx, TI, Motorola and many more! These heat sinks are designed for air flow applications. Enclosed pages have thermal performance data for natural forced convection values.

4 Springs at  
each corner



wakefield-vette  
New Chip Set Heat Sinks



Wakefield-Vette heat sink assembles onto chip set using the space that is between the PCB and the substrate of the solder balls. The solder balls provide a minimal gap of .5mm to .7mm. Attachment feature is below a .4mm thickness. The clipping system will not interfere or damage chip. Contact area is the edge of chip.



Thermal Cooling Solutions from SMART to FINISH

# 901-910 SERIES CHIPSET HEAT SINKS



**Material:** AL 6063

**Finish:** Black Anodize

All dimensions in millimeters (mm)

## Part Numbering System

Series	Chip Size	Construction	Height	Spring Type *	Finish	Interface
<u>901-</u> XXX	<u>19-</u> XX	<u>1-</u> X	<u>12-</u> XX	<u>1-</u> X	<u>B-</u> X	<u>1</u> X

901	19	1= Elliptical Fin	12 = 11.6	1 = .9-2.1 CST	B = BLK ANO	0 = None
902	21	2= Pin Fin	15 = 14.6	2 = 2.2-3.4 CST		1 = T725
903	23		18 = 17.6			
904	27		21 = 20.6			
905	29		23 = 22.6			
906	31		28 = 27.6			
907	33		33 = 32.6			
908	35					
909	37.5					
910	40					

\*Note: When selecting part number chip set thickness (CST) relates to spring selection!



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## THERMAL PERFORMANCE



	HT	CHIP SIZE	PIN FIN				ELLIPTICAL FIN			
			NATURAL CONVECTION	FORCED CONVECTION 200 LFM	400 LFM	600 LFM	NATURAL CONVECTION	FORCED CONVECTION 200 LFM	400 LFM	600 LFM
901	12	19mm	12.74 C/W	6.6 C/W	4.79 C/W	4.16 C/W	14.77 C/W	6.63 C/W	5.09 C/W	4.38 C/W
	15	19mm	12.05 C/W	6.3 C/W	4.51 C/W	3.86 C/W	14 C/W	6.12 C/W	4.63 C/W	3.95 C/W
	18	19mm	11.35 C/W	5.97 C/W	4.16 C/W	3.47 C/W	13.23 C/W	5.67 C/W	4.17 C/W	3.58 C/W
	21	19mm	10.66 C/W	5.66 C/W	3.89 C/W	3.21 C/W	12.46 C/W	5.28 C/W	3.87 C/W	3.24 C/W
	23	19mm	10.55 C/W	5.36 C/W	3.64 C/W	2.99 C/W	11.98 C/W	4.89 C/W	3.58 C/W	3.06 C/W
	28	19mm	10.27 C/W	4.91 C/W	3.36 C/W	2.71 C/W	11.5 C/W	4.38 C/W	3.26 C/W	2.80 C/W
902	33	19mm	9.99 C/W	4.52 C/W	3.07 C/W	2.49 C/W	9.57 C/W	4.04 C/W	2.98 C/W	2.62 C/W
	12	21mm	12.4 C/W	6.61 C/W	4.37 C/W	3.7 C/W	14.31 C/W	5.81 C/W	3.86 C/W	3.16 C/W
	15	21mm	11.73 C/W	5.84 C/W	4.09 C/W	3.42 C/W	13.57 C/W	5.3 C/W	3.5 C/W	2.89 C/W
	18	21mm	11.06 C/W	5.51 C/W	3.76 C/W	3.07 C/W	12.83 C/W	4.95 C/W	3.35 C/W	2.66 C/W
	21	21mm	10.38 C/W	5.20 C/W	3.49 C/W	2.84 C/W	12.09 C/W	4.61 C/W	3.111 C/W	2.47 C/W
	23	21mm	10.27 C/W	4.9 C/W	3.26 C/W	2.62 C/W	11.63 C/W	4.32 C/W	2.91 C/W	2.32 C/W
903	28	21mm	9.98 C/W	4.55 C/W	2.98 C/W	2.42 C/W	10.47 C/W	3.89 C/W	2.61 C/W	2.09 C/W
	33	21mm	9.7 C/W	4.18 C/W	2.73 C/W	2.21 C/W	9.3 C/W	3.57 C/W	2.37 C/W	1.95 C/W
	12	23mm	12.06 C/W	5.72 C/W	3.95 C/W	3.24 C/W	13.85 C/W	4.75 C/W	3.31 C/W	2.79 C/W
	15	23mm	11.41 C/W	5.39 C/W	3.67 C/W	2.99 C/W	13.14 C/W	4.38 C/W	3.05 C/W	2.53 C/W
	18	23mm	10.76 C/W	5.05 C/W	3.35 C/W	2.67 C/W	12.44 C/W	4.07 C/W	2.81 C/W	2.32 C/W
	21	23mm	10.11 C/W	4.74 C/W	3.1 C/W	2.46 C/W	11.73 C/W	3.84 C/W	2.57 C/W	2.11 C/W
904	23	23mm	9.99 C/W	4.44 C/W	2.87 C/W	2.31 C/W	11.28 C/W	3.59 C/W	2.4 C/W	1.97 C/W
	28	23mm	9.70 C/W	4.09 C/W	2.62 C/W	2.12 C/W	10.16 C/W	3.22 C/W	2.17 C/W	1.8 C/W
	33	23mm	9.41 C/W	3.83 C/W	2.43 C/W	1.96 C/W	9.04 C/W	2.93 C/W	1.95 C/W	1.64 C/W
	12	27mm	11.38 C/W	4.84 C/W	3.11 C/W	2.32 C/W	12.93 C/W	4.34 C/W	3 C/W	2.53 C/W
	15	27mm	10.78 C/W	4.48 C/W	2.84 C/W	2.12 C/W	12.29 C/W	4.05 C/W	2.76 C/W	2.29 C/W
	18	27mm	10.17 C/W	4.13 C/W	2.56 C/W	1.88 C/W	11.64 C/W	3.73 C/W	2.5 C/W	2.07 C/W
905	21	27mm	9.56 C/W	3.82 C/W	2.32 C/W	1.72 C/W	11 C/W	3.43 C/W	2.31 C/W	1.9 C/W
	23	27mm	9.44 C/W	3.51 C/W	2.11 C/W	1.6 C/W	10.58 C/W	3.21 C/W	2.11 C/W	1.71 C/W
	28	27mm	9.13 C/W	3.26 C/W	1.97 C/W	1.49 C/W	9.54 C/W	2.89 C/W	1.84 C/W	1.51 C/W
	33	27mm	8.82 C/W	3.07 C/W	1.82 C/W	1.39 C/W	8.51 C/W	2.62 C/W	1.66 C/W	1.35 C/W
	12	29mm	11.04 C/W	4.08 C/W	2.55 C/W	1.98 C/W	12.47 C/W	4.09 C/W	2.74 C/W	2.25 C/W
	15	29mm	10.46 C/W	3.82 C/W	2.32 C/W	1.78 C/W	11.86 C/W	3.81 C/W	2.52 C/W	2.02 C/W
905	18	29mm	9.87 C/W	3.58 C/W	2.14 C/W	1.58 C/W	11.25 C/W	3.56 C/W	2.31 C/W	1.84 C/W
	21	29mm	9.28 C/W	3.33 C/W	1.96 C/W	1.44 C/W	10.63 C/W	3.3 C/W	2.12 C/W	1.65 C/W
	23	29mm	9.16 C/W	3.13 C/W	1.82 C/W	1.34 C/W	10.23 C/W	3.06 C/W	1.91 C/W	1.49 C/W
	28	29mm	8.84 C/W	2.82 C/W	1.64 C/W	1.2 C/W	9.24 C/W	2.72 C/W	1.69 C/W	1.33 C/W
	33	29mm	8.53 C/W	2.59 C/W	1.47 C/W	1.07 C/W	8.24 C/W	2.47 C/W	1.49 C/W	1.18 C/W

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## THERMAL PERFORMANCE



	HT	CHIP SIZE	PIN FIN				ELLIPTICAL FIN				
			NATURAL CONVECTION	FORCED CONVECTION (C/W)			NATURAL CONVECTION	FORCED CONVECTION (C/W)			
			200 LFM	400 LFM	600 LFM	200 LFM	400 LFM	600 LFM	200 LFM	400 LFM	600 LFM
906	12	31mm	10.71 C/W	3.49 C/W	2.28 C/W	1.69 C/W	12.02 C/W	3.37 C/W	2.25 C/W	1.87 C/W	
	15	31mm	10.14 C/W	3.18 C/W	2.03 C/W	1.5 C/W	11.43 C/W	3.13 C/W	2.02 C/W	1.66 C/W	
	18	31mm	9.57 C/W	2.93 C/W	1.86 C/W	1.33 C/W	10.85 C/W	2.85 C/W	1.79 C/W	1.45 C/W	
	21	31mm	9.01 C/W	2.72 C/W	1.69 C/W	1.2 C/W	10.27 C/W	2.63 C/W	1.63 C/W	1.31 C/W	
	23	31mm	8.88 C/W	2.5 C/W	1.54 C/W	1.07 C/W	9.88 C/W	2.44 C/W	1.5 C/W	1.19 C/W	
	28	31mm	8.56 C/W	2.26 C/W	1.38 C/W	.96 C/W	8.93 C/W	2.21 C/W	1.36 C/W	1.05 C/W	
907	33	31mm	8.24 C/W	2.09 C/W	1.27 C/W	.88 C/W	7.98 C/W	2.02 C/W	1.19 C/W	.93 C/W	
	12	33mm	10.37 C/W	3.32 C/W	2.18 C/W	1.62 C/W	11.56 C/W	3.23 C/W	2.09 C/W	1.73 C/W	
	15	33mm	9.82 C/W	3.14 C/W	1.99 C/W	1.45 C/W	11 C/W	2.97 C/W	1.88 C/W	1.54 C/W	
	18	33mm	9.28 C/W	2.89 C/W	1.78 C/W	1.3 C/W	10.45 C/W	2.69 C/W	1.7 C/W	1.37 C/W	
	21	33mm	8.73 C/W	2.67 C/W	1.60 C/W	1.13 C/W	9.9 C/W	2.5 C/W	1.52 C/W	1.22 C/W	
	23	33mm	8.60 C/W	2.45 C/W	1.43 C/W	.99 C/W	9.54 C/W	2.3 C/W	1.37 C/W	1.08 C/W	
908	28	33mm	8.27 C/W	2.24 C/W	1.28 C/W	.87 C/W	8.62 C/W	2.08 C/W	1.23 C/W	.98 C/W	
	33	33mm	7.94 C/W	2.03 C/W	1.15 C/W	.77 C/W	7.71 C/W	1.89 C/W	1.08 C/W	.86 C/W	
	12	35mm	10.03 C/W	3.06 C/W	1.97 C/W	1.49 C/W	11.1 C/W	3.07 C/W	2.07 C/W	1.64 C/W	
	15	35mm	9.5 C/W	2.85 C/W	1.81 C/W	1.34 C/W	10.58 C/W	2.79 C/W	1.87 C/W	1.46 C/W	
	18	35mm	8.98 C/W	2.6 C/W	1.64 C/W	1.19 C/W	10.06 C/W	2.54 C/W	1.69 C/W	1.27 C/W	
	21	35mm	8.46 C/W	2.4 C/W	1.5 C/W	1.07 C/W	9.53 C/W	2.35 C/W	1.52 C/W	1.15 C/W	
909	23	35mm	8.32 C/W	2.19 C/W	1.34 C/W	.97 C/W	8.75 C/W	2.13 C/W	1.35 C/W	1.01 C/W	
	28	35mm	7.99 C/W	1.97 C/W	1.19 C/W	.83 C/W	7.93 C/W	1.94 C/W	1.19 C/W	.86 C/W	
	33	35mm	7.65 C/W	1.82 C/W	1.06 C/W	.7 C/W	7.11 C/W	1.69 C/W	1.02 C/W	.72 C/W	
	12	37.5mm	9.60 C/W	2.93 C/W	1.90 C/W	1.36 C/W	10.52 C/W	3.11 C/W	2.01 C/W	1.61 C/W	
	15	37.5mm	9.11 C/W	2.71 C/W	1.72 C/W	1.19 C/W	10.04 C/W	2.82 C/W	1.79 C/W	1.41 C/W	
	18	37.5mm	8.61 C/W	2.52 C/W	1.53 C/W	1.05 C/W	9.56 C/W	2.59 C/W	1.59 C/W	1.22 C/W	
910	21	37.5mm	8.11 C/W	2.25 C/W	1.36 C/W	.88 C/W	9.08 C/W	2.38 C/W	1.41 C/W	1.06 C/W	
	23	37.5mm	7.98 C/W	2.04 C/W	1.2 C/W	.75 C/W	8.75 C/W	2.15 C/W	1.24 C/W	.94 C/W	
	28	37.5mm	7.63 C/W	1.82 C/W	1.01 C/W	.63 C/W	7.93 C/W	1.88 C/W	1.08 C/W	.8 C/W	
	33	37.5mm	7.29 C/W	1.6 C/W	.87 C/W	.52 C/W	7.11 C/W	1.64 C/W	.93 C/W	.68 C/W	
	12	40mm	9.18 C/W	2.84 C/W	1.86 C/W	1.36 C/W	9.95 C/W	3.09 C/W	1.93 C/W	1.56 C/W	
	15	40mm	8.71 C/W	2.64 C/W	1.65 C/W	1.18 C/W	9.51 C/W	2.77 C/W	1.73 C/W	1.37 C/W	
910	18	40mm	8.24 C/W	2.4 C/W	1.44 C/W	.98 C/W	9.06 C/W	2.74 C/W	1.52 C/W	1.17 C/W	
	21	40mm	7.77 C/W	2.21 C/W	1.27 C/W	.86 C/W	8.62 C/W	2.22 C/W	1.35 C/W	.99 C/W	
	23	40mm	7.63 C/W	2 C/W	1.15 C/W	.73 C/W	8.3 C/W	2.01 C/W	1.19 C/W	.87 C/W	
	28	40mm	7.27 C/W	1.77 C/W	.99 C/W	.62 C/W	7.55 C/W	1.8 C/W	1.04 C/W	.75 C/W	
	33	40mm	6.92 C/W	1.58 C/W	.85 C/W	.51 C/W	6.78 C/W	1.61 C/W	.88 C/W	.64 C/W	

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## 901-910 SERIES CHIPSET HEAT SINKS



### SHOCK TEST SPECIFICATION :

Wave Form : Half sine wave

Acceleration : 50 g

Duration Time : 11 ms

No. of Shock : Each axis 3 times

Shock Direction :  $\pm X$ ,  $\pm Y$ ,  $\pm Z$  axis

Reliability & Communication Testing  
Instruments

### Random Vibration test

Frequency : 5 Hz to 500 Hz

Acceleration : 3.13 grms

P.S.D : 0.01 g<sup>2</sup>/HZ (5 Hz)

0.02 g<sup>2</sup>/HZ (20 Hz to 500 Hz)

Test Axis : X, Y, Z axis

Test Time : 10 mins (Each axis)

Total Test Time : 30 mins



wakefield-vette



**STEP 1:** Center heat Sink onto BGA. Tilt and hook one side of the clip under the BGA chip.



**STEP 2:** Press down the other side of clip to snap it onto the BGA chip.



**STEP :3** Make sure the stop pin is not on top of the chip set. Installation Done!



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## 901-910 SERIES CHIPSET HEAT SINKS



## Contact Us / Corporate Location Information

Wakefield-Vette is Global. Global presence means our engineering, design, sales and support are close to our customers, in the Americas, Europe, Middle East and Asia. It means multi-national manufacturing and delivery. And it means a global Wakefield-Vette supply chain that can deliver, and provide support quickly, anywhere, with the highest quality solutions.

Contact sales for a list of Distributors that carry stock.

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**Thermal Cooling Solutions from SMART to FINISH**

## Данный компонент на территории Российской Федерации

### Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

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